

7700
 7800
 7900
 8000
 8100
 8200
 8300
 8400
 8500
 8600
 8700
 8800
 8900
 9000
 9100
 9200
 9300
 9400
 9500
 9600
 9700
 9800
 9900
 10000

A chip 1 is bonded on a circuit board 4 by aligning in position bumps 3 with board electrodes 5 with interposition of an anisotropic conductive layer 10 in which an insulating resin is mixed with conductive particles 10a and an inorganic filler 6f, and pressing the chip 1 against the board 4 with a pressure force of not smaller than 20 gf per bump applied to the chip 1 against the board 4 by means of a head 8 while correcting warp of the chip and the board and crushing the bumps, and hardening the insulating resin.